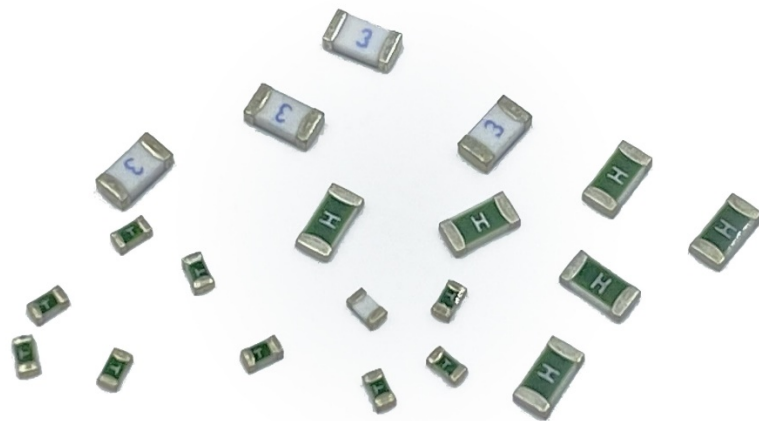


VDK 熔断保险丝

VDK FUSED FUSE



优良品质 · 诚信经营

一起携手 · 共创辉煌

VDKC0402TS TIME-LAG FUSE

DESCRIPTION

VDKC0402TS Series are time-lag fuse, The chip fuses set the industry standard for performance, reliability and quality. The solder-free design provides excellent on-off and temperature cycling characteristics and also makes our chip fuses more heat and shock tolerant than typical subminiature fuses.

FEATURES

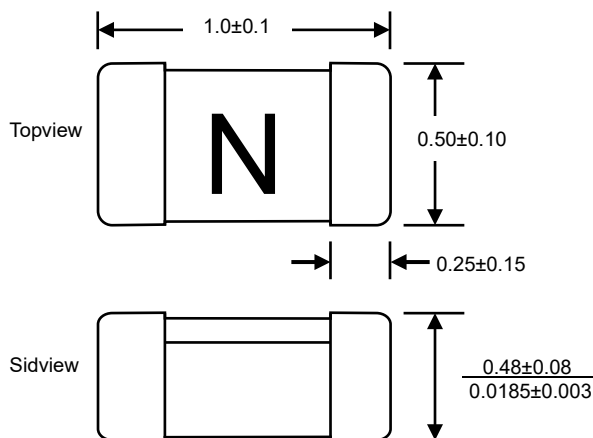
- Time-lag for excessive current
- Compatible with reflow and wave solder
- Ceramic and glass construction
- Excellent environmental integrity
- One time positive disconnect
- Lead Free and Halogen free material

ELECTRICAL CHARACTERISTICS

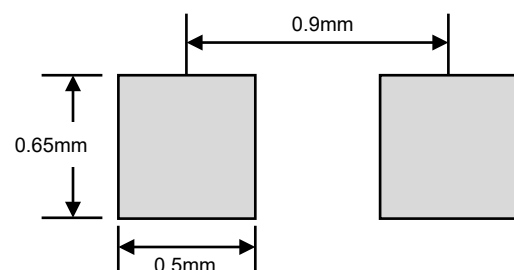
Rated Current	1.0In	2.5In	3.5In
1A~4A 200mA~750mA	4 hour min.	5 sec max. -	- 5 sec max.

DIMENSIONS

Drawing not to scale (Unit: mm/inch)



Recommended land pattern:



Print solder in thickness of 0.08mm to 0.10mm

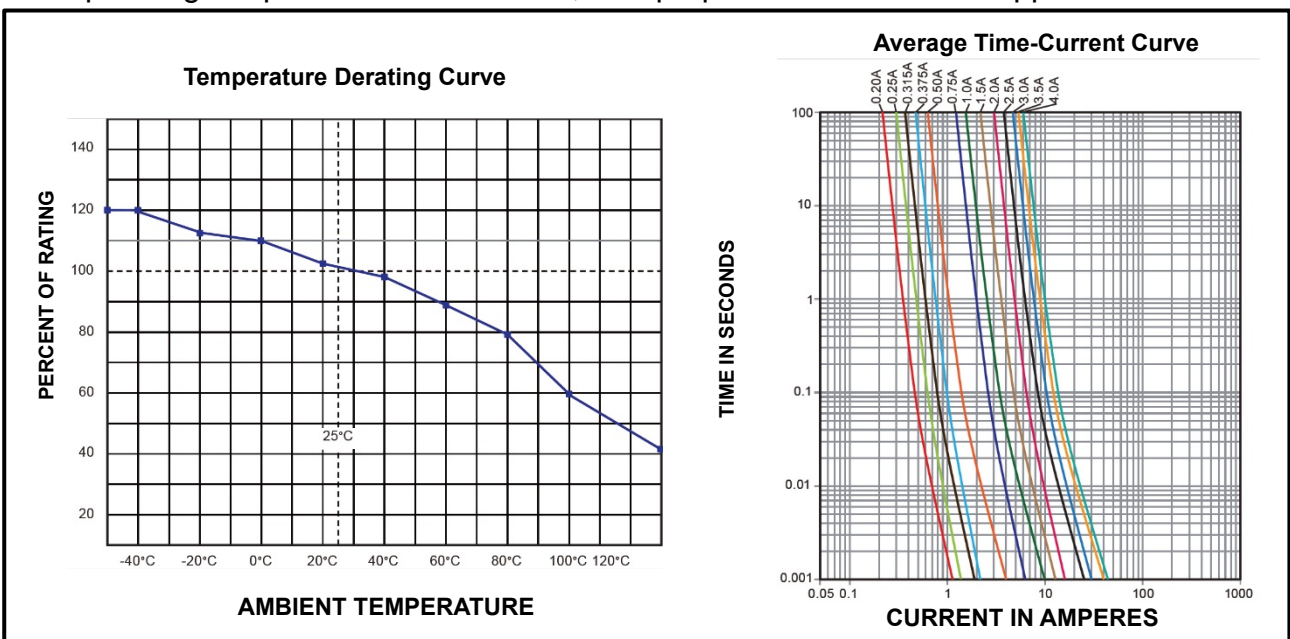
PERFORMANCE SPECIFICATIONS

Part No.	Rated Current (A)	Rated Voltage DC	Interrupting Rating	Resistance (mK)**Typ	Typical Melt I^2t ** (A ² sec)
VDKC0402-0200TS	0.20	32V	35A	2250	0.0006
VDKC0402-0250TS	0.25			1500	0.0010
VDKC0402-0315TS	0.315			1000	0.0014
VDKC0402-0375TS	0.375			780	0.0018
VDKC0402-0500TS	0.50			500	0.0043
VDKC0402-0750TS	0.75			220	0.011
VDKC0402-1100TS	1.0			130	0.04
VDKC0402-1150TS	1.5			78	0.06
VDKC0402-1200TS	2.0			40	0.13
VDKC0402-1250TS	2.5			24	0.20
VDKC0402-1300TS	3.0			18	0.33
VDKC0402-1350TS	3.5			14	0.45
VDKC0402-1400TS	4.0			11	0.60

- * DC Interrupting Rating (Measured at rated voltage, time constant of less than 50 microseconds, battery source)
- * DC Cold Resistance are measured at <10% of rated current in ambient temperature of 25°C
- * Typical Melting I^2t (Measured with a battery bank at rated DC voltage, Measured at 1ms open time, time constant of calibrated circuit less than 50 microseconds).

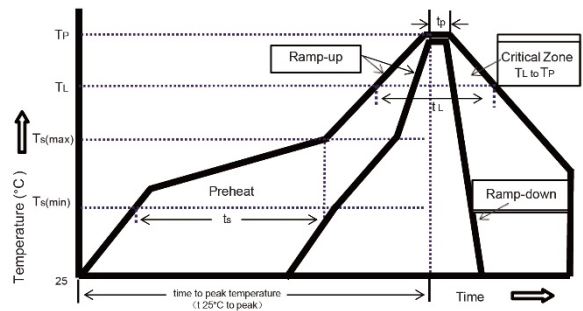
ENVIRONMENTAL CHARACTERISTIC

- Normal ambient temperature: 23+/-3°C
- Operating temperature: -55 ~ 150°C, with proper correction factor applied



SOLDERING PARAMETERS

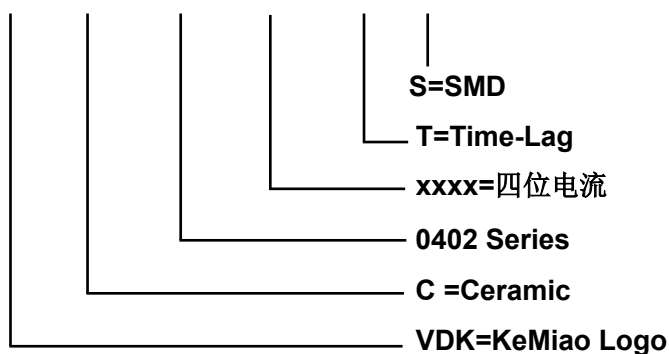
Profile Feature		Lead(Pb) free solder
Preheat and soak	-Temperature min (T_{smin})	150°C
	-Temperature max (T_{smax})	200°C
	-Time (T_{smin} to T_{smax}) (ts)	60~120 Secs
Average ramp up rate T_{smax} to T_P		3°C/Secs Max
Liquidous temperature (T_L) Time at liquidous (t_L)		270°C 60~150 Secs
Peak package body temperature (T_P)		260°C
Time (t_p) within 5°C of the specified classification temperature (T_C)		30 Secs
Average ramp-down rate (T_P to T_{smax})		6°C/Secs Max
Time (25°C to Peak Temperature)		8 Minutes Max



Soldering Method		Parameter
Wave solder	Reservoir temperature	260°C
	Time in reservoir	10 Secs max
Infrared reflow	Temperature	260°C
	Time	30 Secs max

PACKING

No.	Quantity & Packaging Code
VDKC0402TS	10000 fuses/reel (8mm tape-and-reel on a 7 inch (178mm) reel per EIA Standard 481)

PART NUMBERING SYSTEM
VDK C 0402-xxxx T S

OTHERS

- If in use beyond the requirements of the specifications, must pass through the mutual confirmation!
- If the specification is not appropriate, must through consultation between the two sides and by the company to modify.
- It could be in conformance with another file which made by our company.